

Notification Number:	20260925000.0	Notification Issued	September 28, 2026
Datasheet for LP5817, LP5814, LP5814I, LP5815, and LP5816			

Change Type(s)	Data Sheet/Electrical Specification
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Notification Details

Description of Change:	
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.	
	LP5817 SNVSCQ2B – MARCH 2025 – REVISED SEPTEMBER 2026
Changes from Revision A (August 2025) to Revision B (September 2026)	Page
• Deleted device-to-device error description in <i>Features</i> section.....	1
• Changed I2C address of LP5814IYCHR from 0x2C to 0x2E in Device Comparison Table.....	3
• Update Thermal Information table in the <i>Specifications</i> section.....	5
• Update Electrical Characteristics table in the <i>Specifications</i> section.....	5
	LP5814 SNVSCQ0A – MARCH 2025 – REVISED SEPTEMBER 2026
Changes from Revision * (March 2025) to Revision A (September 2026)	Page
• Delete device-to-device error description in the <i>Features</i> section.....	1
• Changed I2C address of LP5814IYCHR from 0x2C to 0x2E in Device Comparison Table.....	3
• Update Thermal Information table in the <i>Specifications</i> section.....	5
• Update Electrical Characteristics table in the <i>Specifications</i> section.....	5
	LP5814I SNVSD24A – AUGUST 2025 – REVISED SEPTEMBER 2026
Changes from Revision * (March 2025) to Revision A (September 2026)	Page
• Deleted device-to-device error description in the <i>Features</i> section.....	1
• Changed I2C address of LP5814IYCHR from 0x2C to 0x2E in Device Comparison Table.....	3
• Updated Thermal Information table in Specifications.....	5
• Updated Electrical Characteristics table in Specifications.....	5
	LP5815 SNVSCP2B – MARCH 2025 – REVISED SEPTEMBER 2026
Changes from Revision A (August 2025) to Revision B (September 2026)	Page
• Delete device-to-device error description in Feature.....	1
• Changed I2C address of LP5814IYCHR from 0x2C to 0x2E in Device Comparison Table.....	3
• Update Thermal Information table in the <i>Specifications</i> section.....	5
• Update Electrical Characteristics table in the <i>Specifications</i> section.....	5

Changes from Revision A (April 2025) to Revision B (September 2026)
Page

- Deleted device-to-device error description in the *Features* section.....1
- Changed I2C address of LP5814IYCHR from 0x2C to 0x2E in Device Comparison Table..... 3
- Update Thermal Information table in the *Specifications* section.....5
- Update Electrical Characteristics table in the *Specifications* section..... 5

The datasheet number will be changing.

Device Family	Change From:	Change To:
LP5817	SNVSCQ2A	SNVSCQ2B
LP5814	SNVSCQ0	SNVSCQ0A
LP5814I	SNVSD24	SNVSD24A
LP5815	SNVSCP2A	SNVSCP2B
LP5816	SNVSCQ1A	SNVSCQ1B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/LP5817>

<http://www.ti.com/product/LP5814>

<http://www.ti.com/product/LP5814I>

<http://www.ti.com/product/LP5815>

<http://www.ti.com/product/LP5816>

Reason for Change:

To accurately reflect device characteristics

Anticipated impact on Form, Fit, Function, Quality or Reliability:

None

Changes to product identification resulting from this PCN:

None

Products Affected:

LP5817DRLR	LP5814DRLR	LP5815DRLR	LP5814DRLR.A
LP5817DRLR.A	LP5817YCHR	LP5816YCHR	LP5816DRLR.A
LP5815DRLR.A	LP5814YCHR	LP5816DRLR	LP5814IYCHR
LP5815YCHR			

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

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